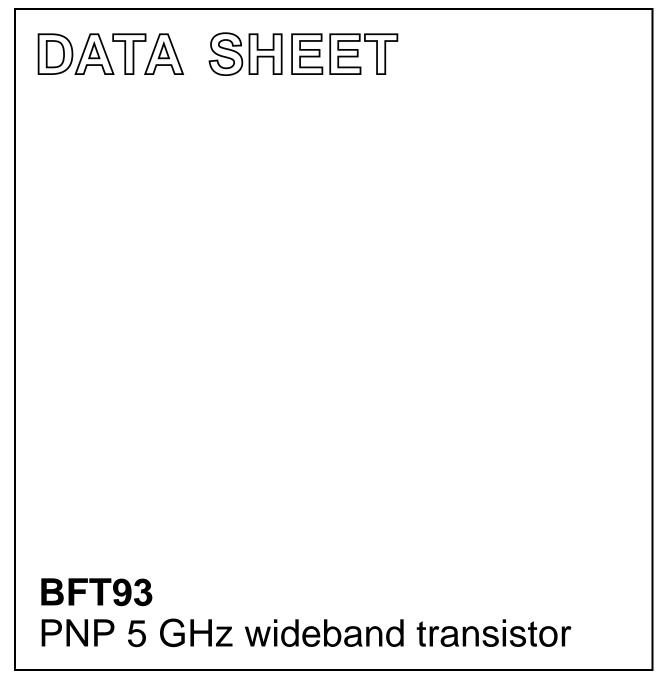
DISCRETE SEMICONDUCTORS



Product specification

November 1992



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#### Note

1. T<sub>s</sub> is the temperature at the soldering point of the collector tab.

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-15	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-12	V
I <sub>c</sub>	DC collector current		_	-35	mA
P <sub>tot</sub>	total power dissipation	up to T <sub>s</sub> = 95 °C; note 1	_	300	mW
f <sub>T</sub>	transition frequency	$I_C = -30$ mA; $V_{CE} = -5$ V; f = 500 MHz; T <sub>j</sub> = 25 °C	5	-	GHz
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = -2 mA; V <sub>CE</sub> = -5 V; f = 1 MHz	1	_	pF
G <sub>UM</sub>	maximum unilateral power gain	$ I_{C} = -30 \text{ mA}; V_{CE} = -5 \text{ V}; f = 500 \text{ MHz}; $ 16. $ T_{amb} = 25 \text{ °C} $		-	dB
F	noise figure	$I_{C} = -10 \text{ mA}; V_{CE} = -5 \text{ V}; f = 500 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$		-	dB
Vo	output voltage	$\begin{array}{l} {d_{im} = -60 \text{ dB}; \text{ I}_{\text{C}} = -30 \text{ mA};} \\ {V_{\text{CE}} = -5 \text{ V}; \text{ R}_{\text{L}} = 75 \Omega;} \\ {f_{(p+q-r)} = 493.25 \text{ MHz}} \end{array}$	300	-	mV

### DESCRIPTION

PNP transistor in a plastic SOT23 envelope.

It is primarily intended for use in RF wideband amplifiers, such as in aerial oscilloscopes, spectrum analyzers, etc. The transistor features low intermodulation distortion and high power gain; due to its very high transition frequency, it also has excellent wideband properties and

amplifiers, radar systems,

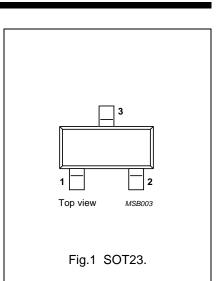
low noise up to high frequencies.

NPN complements are BFR93 and BFR93A.

#### PIN DESCRIPTION Code: X1p 1 base

PINNING

2 emitter 3 collector



**PNP 5 GHz wideband transistor** 

### BFT93

#### LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-15	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-12	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-2	V
I <sub>C</sub>	DC collector current		-	-35	mA
I <sub>CM</sub>	peak collector current	f > 1 MHz	-	-50	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 95 \text{ °C}$ ; note 1	-	300	mW
T <sub>stg</sub>	storage temperature		-65	150	°C
Tj	junction temperature		-	175	°C

#### THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
	thermal resistance from junction to soldering point	up to $T_s = 70 \ ^\circ C$ ; (note 1)	260 K/W

#### Note

1.  $T_s$  is the temperature at the soldering point of the collector tab.

### BFT93

#### CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

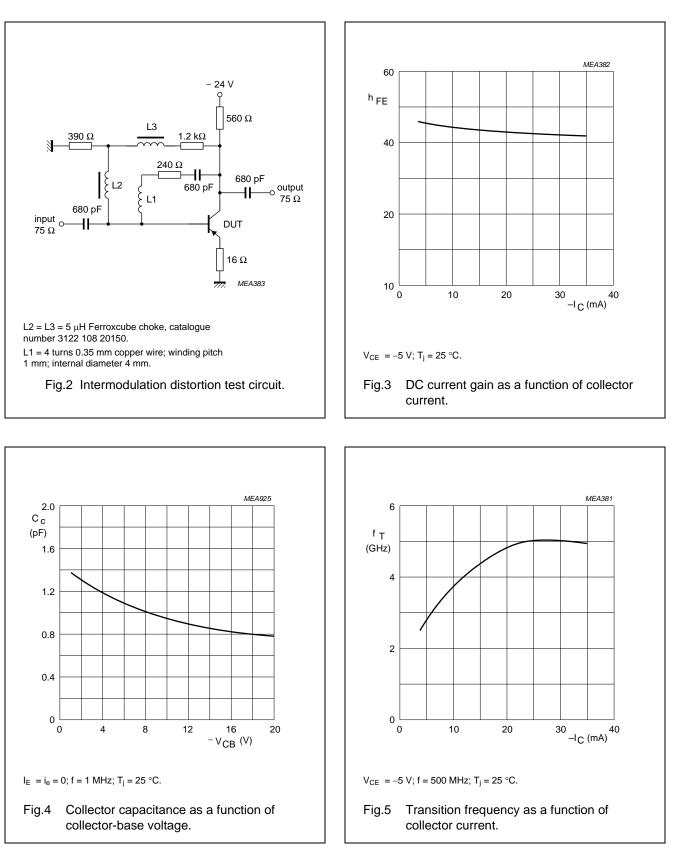
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	$I_{E} = 0; V_{CB} = -5 V$	-	-	-50	nA
h <sub>FE</sub>	DC current gain	$I_{C} = -30 \text{ mA}; V_{CE} = -5 \text{ V}$	20	50	-	
f <sub>T</sub>	transition frequency	$I_{C} = -30 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 500 MHz	-	5	-	GHz
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0; V_{CB} = -10 V; f = 1 MHz$	_	0.95	_	pF
C <sub>e</sub>	emitter capacitance	$I_c = i_c = 0; V_{EB} = -0.5 V; f = 1 MHz$	-	1.8	-	pF
C <sub>re</sub>	feedback capacitance	$I_{C} = -2 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ f} = 1 \text{ MHz}$	-	1	-	pF
G <sub>UM</sub>	maximum unilateral power gain (note 1)	I <sub>C</sub> = -30 mA; V <sub>CE</sub> = -5 V; f = 500 MHz; T <sub>amb</sub> = 25 °C	-	16.5	_	dB
F	noise figure	I <sub>C</sub> = -10 mA; V <sub>CE</sub> = -5 V; f = 500 MHz; T <sub>amb</sub> = 25 °C	-	2.4	-	dB
Vo	output voltage	see Fig.2 and note 2	-	300	_	mV

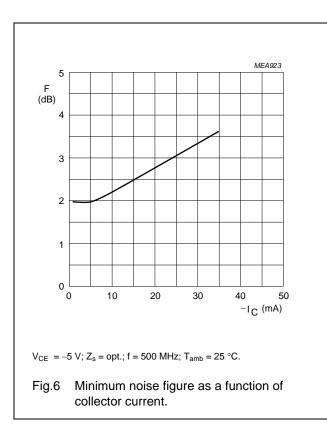
#### Notes

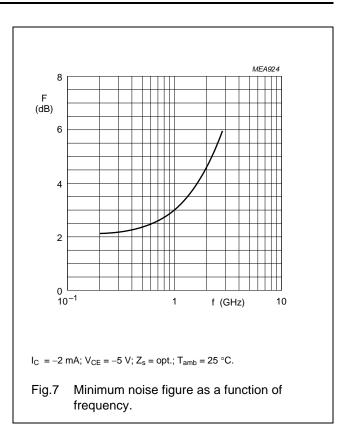
1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $S_{12}$  is zero and

$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} dB.$$

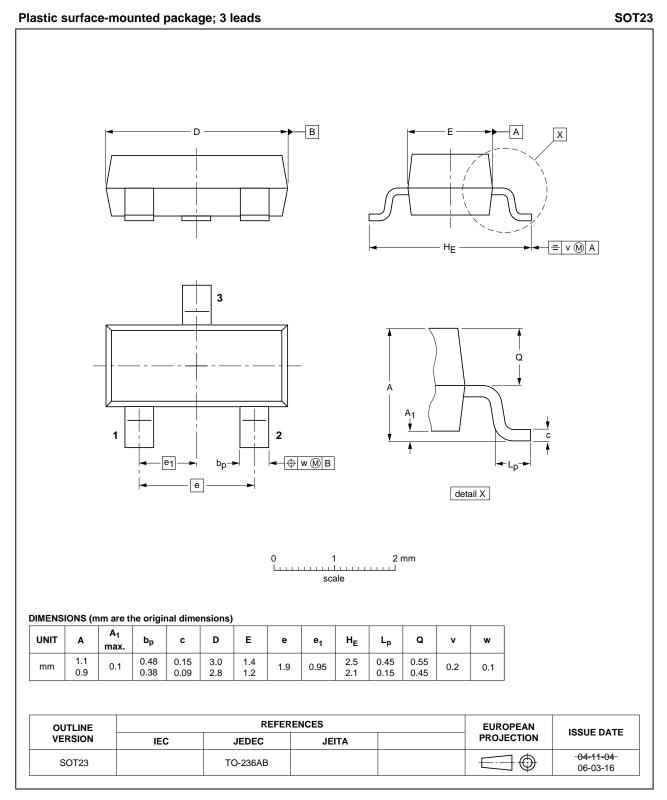
2.  $d_{im} = -60 \text{ dB} \text{ (DIN 45004B)}; I_C = -30 \text{ mA}; V_{CE} = -5 \text{ V}; R_L = 75 \Omega;$   $V_p = V_o \text{ at } d_{im} = -60 \text{ dB}; f_p = 495.25 \text{ MHz};$   $V_q = V_o -6 \text{ dB}; f_q = 503.25 \text{ MHz};$   $V_r = V_o -6 \text{ dB}; f_r = 505.25 \text{ MHz};$ measured at  $f_{(p+q-r)} = 493.25 \text{ MHz}.$ 







#### PACKAGE OUTLINE



BFT93

#### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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#### **Contact information**

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